

# NE5550779A

R09DS0040EJ0300 Rev.3.00 Mar 12, 2013

# **FEATURES**

- High Output Power
- :  $P_{out}$  = 38.5 dBm TYP. ( $V_{DS}$  = 7.5 V,  $I_{Dset}$  = 140 mA, f = 460 MHz,  $P_{in}$  = 25 dBm)
- High power added efficiency
- High Linear gain
- High ESD tolerance
- Suitable for VHF to UHF-BAND Class-AB power amplifier.

#### APPLICATIONS

- 150 MHz Band Radio System
- 460 MHz Band Radio System
- 900 MHz Band Radio System

#### ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
NE5550779A	NE5550779A-A	79A	W8	<ul> <li>12 mm wide embossed taping</li> </ul>
		(Pb-Free)		<ul> <li>Gate pin faces the perforation side of the tape</li> </ul>
NE5550779A-T1	NE5550779A-T1-A			12 mm wide embossed taping
				<ul> <li>Gate pin faces the perforation side of the tape</li> </ul>
				Qty 1 kpcs/reel
NE5550779A-T1A	NE5550779A-T1A-A			12 mm wide embossed taping
				<ul> <li>Gate pin faces the perforation side of the tape</li> </ul>
				Qty 5 kpcs/reel

**Remark** To order evaluation samples, please contact your nearby sales office.

Part number for sample order: NE5550779A

# ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C, unless otherwise specified)

Operation in excess of any one of these parameters may result in permanent damage.

Parameter	Symbol	Ratings	Unit
Drain to Source Voltage	V <sub>DS</sub>	30	V
Gate to Source Voltage	V <sub>GS</sub>	6.0	V
Drain Current	I <sub>DS</sub>	2.1	А
Drain Current	I <sub>DS-pulse</sub>	4.2	А
(50% Duty Pulsed)			
Total Power Dissipation Note	Ptot	17.8	W
Channel Temperature	T <sub>ch</sub>	150	°C
Storage Temperature	T <sub>stg</sub>	–55 to +150	°C

Note: Value at  $T_C = 25^{\circ}C$ 

#### CAUTION

Observe precautions when handling because these devices are sensitive to electrostatic discharge.

The mark <R> shows major revised points.

The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.



# **RECOMMENDED OPERATING RANGE (T<sub>A</sub> = 25^{\circ}C)**

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Drain to Source Voltage	V <sub>DS</sub>		-	7.5	9.0	V
Gate to Source Voltage	V <sub>GS</sub>		1.65	2.20	2.85	V
Drain Current	I <sub>DS</sub>		-	1.4	-	Α
Input Power	Pin	f = 460 MHz, V <sub>DS</sub> = 7.5 V	_	25	30	dBm

# ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
DC Characteristics	-		1			
Gate to Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = 6.0 V	-	-	100	nA
Drain to Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> = 25 V	_	_	10	μA
(Zero Gate Voltage Drain Current)						
Gate Threshold Voltage	V <sub>th</sub>	V <sub>DS</sub> = 7.5 V, I <sub>DS</sub> = 1.0 mA	1.15	1.65	2.25	V
Drain to Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>DS</sub> = 10 μA	25	38	-	V
Transconductance	Gm	V <sub>DS</sub> = 7.5 V, I <sub>DS</sub> = 490±70 mA	1.26	1.54	2.03	S
Thermal Resistance	R <sub>th</sub>	Channel to Case	-	7.0	_	°C/W
RF Characteristics						
Output Power	Pout	f = 460 MHz, V <sub>DS</sub> = 7.5 V,	37.0	38.5	_	dBm
Drain Current	I <sub>DS</sub>	P <sub>in</sub> = 25 dBm,	_	1.38	_	Α
Power Drain Efficiency	$\eta_{d}$	I <sub>Dset</sub> = 140 mA (RF OFF)	_	68	_	%
Power Added Efficiency	$\eta_{add}$		_	66	_	%
Linear Gain	GL Note 1		_	22.0	_	dB
Load VSWR Tolerance	Note 2	f = 460 MHz, V <sub>DS</sub> = 9.0 V,	1	lo Destro	y	
		P <sub>in</sub> = 25 dBm,				
		I <sub>Dset</sub> = 140 mA (RF OFF)				
		Load VSWR=20:1(All Phase)				
Output Power	Pout	f = 157 MHz, V <sub>DS</sub> = 7.5 V,	-	38.5	-	dBm
Drain Current	I <sub>DS</sub>	P <sub>in</sub> = 23 dBm,	-	1.36	-	Α
Power Drain Efficiency	$\eta_{d}$	I <sub>Dset</sub> = 140 mA (RF OFF)	-	69	-	%
Power Added Efficiency	$\eta_{add}$		-	67	-	%
Linear Gain	GL <sup>Note 3</sup>		-	24.0	-	dB
Output Power	Pout	f = 900 MHz, V <sub>DS</sub> = 7.5 V,	-	37.4	-	dBm
Drain Current	I <sub>DS</sub>	P <sub>in</sub> = 27 dBm,	-	1.26	-	А
Power Drain Efficiency	$\eta_{d}$	I <sub>Dset</sub> = 140 mA (RF OFF)	-	58	-	%
Power Added Efficiency	$\eta_{add}$		-	53	-	%
Linear Gain	GL Note 4		_	17.0	-	dB

Notes: 1.  $P_{in}$  = 10 dBm

2. These characteristics values are measurement using measurement tools especially by RENESAS.

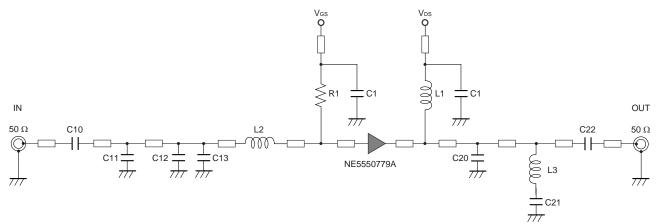
3. P<sub>in</sub> = 5 dBm

4. P<sub>in</sub> = 10 dBm

**Remark** DC performance is 100% testing. RF performance is testing several samples per wafer. A wafer rejection criterion for standard devices is 1 reject for several samples.



# TEST CIRCUIT SCHEMATIC FOR 460 MHz

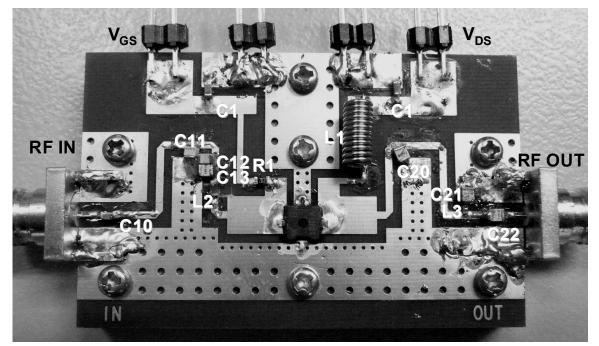


#### COMPONENTS OF TEST CIRCUIT FOR MEASURING ELECTRICAL CHARACTERISTICS

Symbol	Value	Туре	Maker
C1	1 <i>μ</i> F	GRM188B31C105KA92	Murata
C10	27 pF	GRM1882C1H270JA01	Murata
C11	2.7 pF	ATC100A2R7JW	American Technical Ceramics
C12	12 pF	ATC100A120BW	American Technical Ceramics
C13	12 pF	ATC100A120BW	American Technical Ceramics
C20	24 pF	ATC100A240JW	American Technical Ceramics
C21	6.8 pF	ATC100A6R8BW	American Technical Ceramics
C22	100 pF	ATC100A101JW	American Technical Ceramics
R1	2 kΩ	1/10 W Chip Resistor RK73B1JTTD202J	КОА
L1	114 nH	$\phi$ 0.5 mm, $\phi$ D = 3 mm, 10 Turns	Ohesangyou
L2	4.7 nH	LQW18AN4R7NG00	Murata
L3	3.0 nH	LQP15MN3N0B02	Murata
PCB	_	R1766, t = 0.4 mm, <i>ε</i> r = 4.5, size = 30 × 48 mm	Panasonic
SMA Connecter	-	WAKA 01K0790-20	WAKA



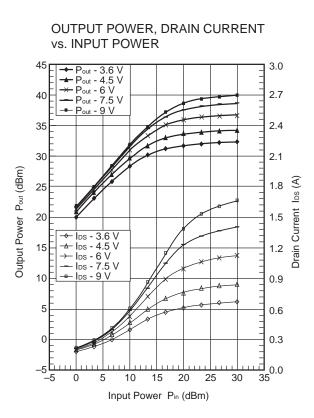
# COMPONENT LAYOUT OF TEST CIRCUIT FOR 460 MHz





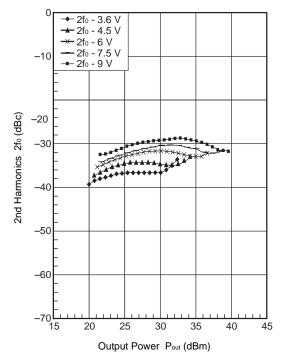
#### TYPICAL CHARACTERISTICS 1 ( $T_A = 25^{\circ}C$ )

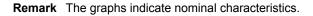
- R: f = 460MHz,  $V_{DS} = 3.6/4.5/6/7.5/9$  V,  $I_{Dset} = 140$  mA,  $P_{in} = 0$  to 30 dBm
- IM: f1 = 460MHz, f2 = 461 MHz,  $V_{DS}$  = 3.6/4.5/6/7.5/9 V,  $I_{Dset}$  = 140mA,  $P_{out}$  (2 tone) = 12 to 37 dBm



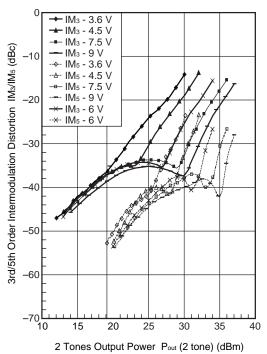
POWER GAIN, POWER ADDED EFFICIENCY vs. INPUT POWER 80 40 ← G<sub>P</sub> - 3.6 V \_\_\_\_\_G<sub>P</sub> - 4.5 V ← Gp - 6 V 35 70 Gp - 7.5 V 🗝 Gp - 9 V η add - 3.6 V 🛨 η add - 4.5 V 30 60 <del>×−</del> η add - 6 V η<sub>add</sub> (%) *–* η add - 7.5 ∖ **–** η add - 9 V G (dB) 25 50 Power Added Efficiency Power Gain 20 40 30 15 10 20 10 5 οĽ 0 0 5 10 15 20 25 30 35 -5 Input Power Pin (dBm)

2fo vs. OUTPUT POWER



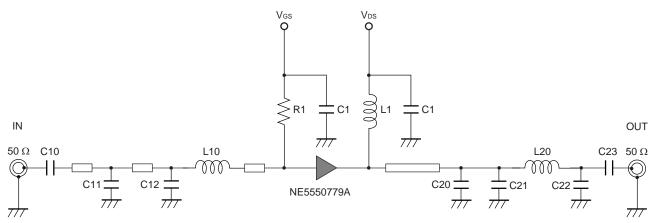


IM3/IM5 vs. 2 TONES OUTPUT POWER





## **TEST CIRCUIT SCHEMATIC FOR 157 MHz**



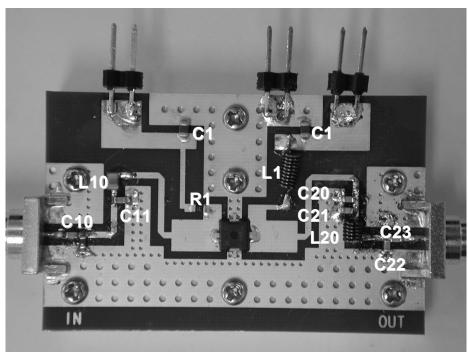
#### COMPONENTS OF TEST CIRCUIT FOR MEASURING ELECTRICAL CHARACTERISTICS

Symbol	Value	Туре	Maker
C1	1 <i>μ</i> F	GRM31MB11E105KA01	Murata
C10	100 pF	GQM1882C1H101JB01	Murata
C11	5.6 pF	GQM1882C2A5R6DB01	Murata
C12	39 pF	GQM1882C1H390JB01	Murata
C20	22 pF	GRM1882C1H220JA01	Murata
C21	68 pF	GQM1882C1H680JB01	Murata
C22	15 pF	GQM1882C1H150JA01	Murata
C23	100 pF	GQM1882C1H101JB01	Murata
R1	5.1 kΩ	1/10 W Chip Resistor	ROAM
		MCR03J103	
L1	74.7 nH	$\phi$ 0.4 mm, $\phi$ D = 2 mm, 10 Turns	Ohesangyou
L10	27 nH	LLQ2012-F27N	Toko
L20	29.8 nH	$\phi$ 0.4 mm, $\phi$ D = 2 mm, 5 Turns	Ohesangyou
PCB	_	R1766, t = 0.4 mm, <i>ε</i> r = 4.5, size = 30 × 48 mm	Panasonic
SMA Connecter	-	WAKA 01K0790-20	WAKA

<R>



# COMPONENT LAYOUT OF TEST CIRCUIT FOR 157 MHz



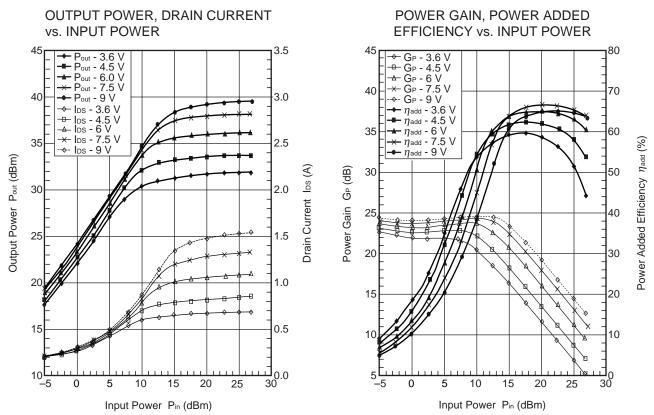
OUT

IN



# TYPICAL CHARACTERISTICS 2 ( $T_A = 25^{\circ}C$ )

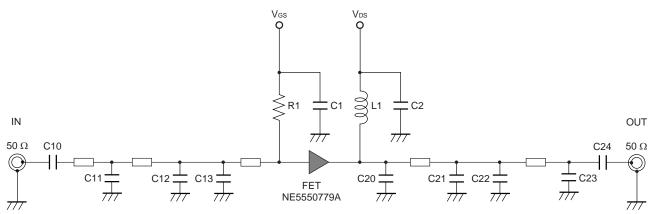
#### RF: $f = 157 \text{ MHz}, V_{DS} = 3.6/4.5/6/7.5/9 \text{ V}, I_{Dset} = 40 \text{ mA}, P_{in} = -10 \text{ to } 20 \text{ dBm}$







#### **TEST CIRCUIT SCHEMATIC FOR 900 MHz**

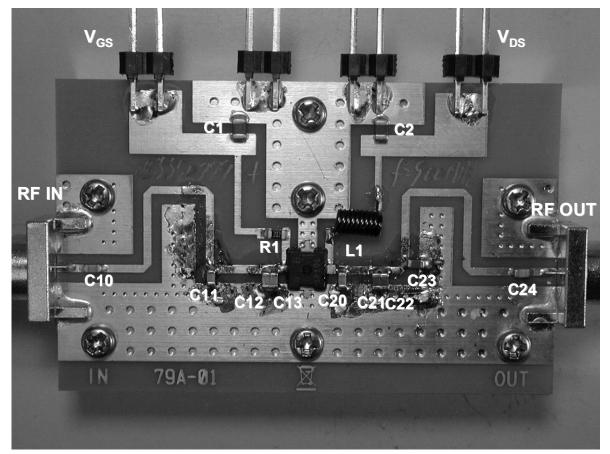


#### COMPONENTS OF TEST CIRCUIT FOR MEASURING ELECTRICAL CHARACTERISTICS

Symbol	Value	Туре	Maker
C10	27 pF	GQM1882C1H270JB01	Murata
C11	6.8 pF	GQM1882C2A6R8DB01	Murata
C12	15 pF	GQM1882C1H150JB01	Murata
C13	18 pF	GQM1882C1H180JB01	Murata
C20	8.2 pF	GQM1882C1H8R2DB01	Murata
C21	3.9 pF	GQM1883C2A3R9CB01	Murata
C22	1.5 pF	GQM1884C2A1R5CB01	Murata
C23	8.2 pF	GQM1882C1H8R2DB01	Murata
C24	100 pF	GQM1882C1H101JB01	Murata
C1	1 <i>µ</i> F	GRM21BB31H105KA2L	Murata
C2	1 <i>µ</i> F	GRM21BB31H105KA2L	Murata
L1	74.7 nH	D20-74N7	Ohesangyou
R1	20 kΩ	MCR03J203	Rohm
PCB	_	R1766, t = 0.8 mm, <i>ε</i> r = 4.8, size = 30 × 40 mm	Panasonic
SMA Connecter	_	WAKA 01K0790-20	WAKA



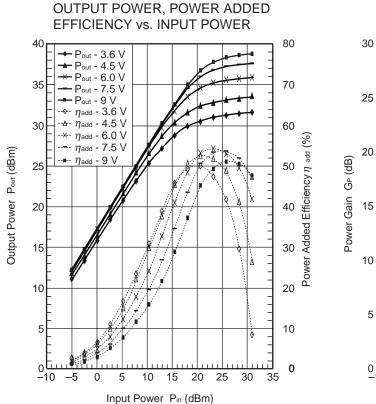
# COMPONENT LAYOUT OF TEST CIRCUIT FOR 900 MHz

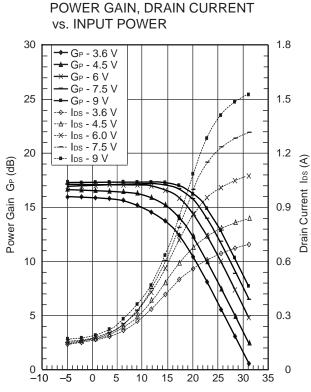




## TYPICAL CHARACTERISTICS 3 ( $T_A = 25^{\circ}C$ )

#### RF: f = 900 MHz, $V_{DS}$ = 3.6/4.5/6/7.5/9 V, $I_{Dset}$ = 40 mA, $P_{in}$ = -5 to 30 dBm





Input Power Pin (dBm)

**Remark** The graphs indicate nominal characteristics.



# **S-PARAMETERS**

S-parameters and noise parameters are provided on our web site in a form (S2P) that enables direct import of the parameters to microwave circuit simulators without the need for keyboard inputs.

Click here to download S-parameters.

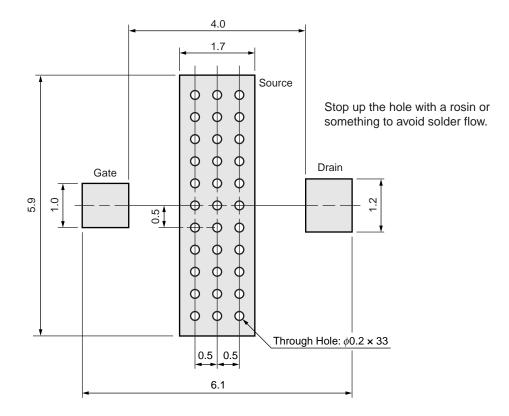
 $[\mathsf{Products}] \to [\mathsf{RF} \ \mathsf{Devices}] \to [\mathsf{Device} \ \mathsf{Parameters}]$ 

URL http://www.renesas.com/products/microwave/



## MOUNTING LAYOUT PAD DIMENSIONS

#### 79A (UNIT: mm)

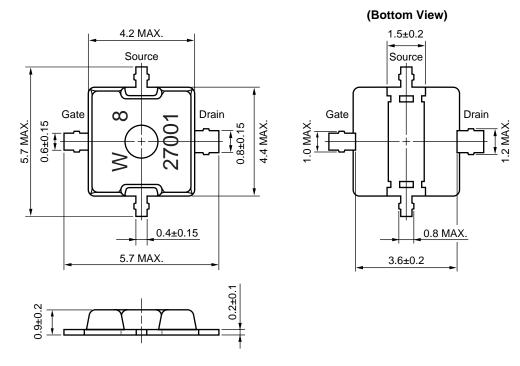


Remark The mounting pad layout in this document is for reference only. When designing PCB, please consider workability of mounting, solder joint reliability, prevention of solder bridge and so on, in order to optimize the design.



# PACKAGE DIMENSIONS

79A (UNIT: mm)





# **RECOMMENDED SOLDERING CONDITIONS**

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature)	: 260°C or below	IR260
	Time at peak temperature	: 10 seconds or less	
	Time at temperature of 220°C or higher	: 60 seconds or less	
	Preheating time at 120 to 180°C	: 120±30 seconds	
	Maximum number of reflow processes	: 3 times	
	Maximum chlorine content of rosin flux (% mass)	: 0.2% (Wt.) or below	
Wave Soldering	Peak temperature (molten solder temperature)	: 260°C or below	WS260
	Time at peak temperature	: 10 seconds or less	
	Preheating temperature (package surface temperature)	ature)	
		: 120°C or below	
	Maximum number of flow processes	: 1 time	
	Maximum chlorine content of rosin flux (% mass)	: 0.2% (Wt.) or below	
Partial Heating	Peak temperature (terminal temperature)	: 350°C or below	HS350
	Soldering time (per side of device)	: 3 seconds or less	
	Maximum chlorine content of rosin flux (% mass)	: 0.2% (Wt.) or below	

#### CAUTION

Do not use different soldering methods together (except for partial heating).



**Revision History** 

# NE5550779A Data Sheet

		Description	
Rev.	Date	Page	Summary
1.00	Apr 26, 2012	-	First edition issued
2.00	Jul 04, 2012	p.2	Modification of ELECTRICAL CHARACTERISTICS
		p.6	Modification of COMPONENTS OF TEST CIRCUIT FOR MEASURING ELECTRICAL CHARACTERISTICS
3.00	Mar 12, 2013	P3	Modification of COMPONENTS OF TEST CIRCUIT FOR MEASURING ELECTRICAL CHARACTERISTICS
		P6	Modification of COMPONENTS OF TEST CIRCUIT FOR MEASURING ELECTRICAL CHARACTERISTICS
		P9	Modification of COMPONENTS OF TEST CIRCUIT FOR MEASURING ELECTRICAL CHARACTERISTICS

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